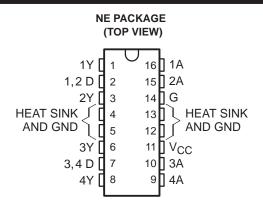
SLRS019B - DECEMBER 1986 - REVISED SEPTEMBER 2000

- Saturating Outputs With Low On-State Resistance
- High-Impedance Inputs Compatible With CMOS and TTL Levels
- Very Low Standby Power . . . 21 mW Max
- High-Voltage Outputs . . . 70 V Min
- No Power-Up or Power-Down Output Glitch
- No Latch-Up Within Recommended Operating Conditions
- Output-Clamp Diodes for Transient Suppression
- Packaged in 2-W Power, Thermally Enhanced Plastic DIP



### description

The SN75437A quadruple peripheral driver is designed for use in systems requiring high current, high voltage, and high load power. This device features four inverting open-collector outputs with a common-enable (G) input that, when taken low, disables all four outputs. The envelope of 1-V characteristics exceeds the specifications sufficiently to avoid high-current latch-up. Applications include driving relays, lamps, solenoids, motors, LEDs, transmission lines, hammers, and other high-power-demand devices.

The SN75437A is characterized for operation over the free-air temperature range of 0°C to 70°C.

# FUNCTION TABLE (each NAND driver)

INP	UTS	OUTPUT
Α	G	Υ
Н	Н	L
L	Χ	Н
Х	L	Н

H = high level, L = low level,

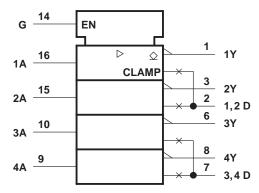
X = irrelevant



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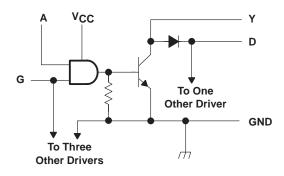
### logic diagram (positive logic)†

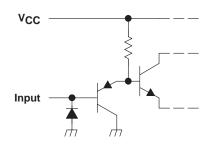


<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC publication 617-12.

# logic diagram (positive logic, each driver)

### equivalent schematic of each input





# absolute maximum ratings over operating temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	
Output current (see Note 1)	0.75 A
Output clamp-diode current, I <sub>OK</sub>	1.25 A
Output voltage, VO (off state)	70 V
Continuous total power dissipation at (or below) 25°C free-air temperature (see Note 2) .	2075 mW
Lead temperature 1,6 mm (1/16-inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stg</sub>	65°C to 150°C

NOTES: 1. All four sections of these circuits may conduct rated current simultaneously; however, power dissipation averaged over a short time interval must fall within the continuous dissipation ratings.

2. For operation above 25°C free-air temperature, derate linearly to 1328 mW at 70°C at the rate of 16.6 mW/°C.

## recommended operating conditions

PARAMETER	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, V <sub>IL</sub>			0.8	V
Output supply voltage in inductive switching circuit (see Figure 2), V <sub>S</sub>			35	٧
Output current, IO			0.5	А
Operating free-air temperature, T <sub>A</sub>	0		70	°C



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

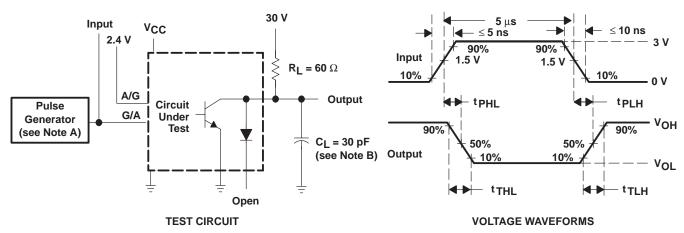
	PARAMETER	TEST CO	MIN	TYP†	MAX	UNIT	
VIK	Input clamp voltage	$V_{CC} = 4.75 \text{ V},$	$I_{I} = -12 \text{ mA}$		-0.9	-1.5	V
V.0.	Low-level output voltage	V <sub>CC</sub> = 4.75 V,	I <sub>OL</sub> = 250 mA		0.14	0.25	V
VOL	Low-level output voltage	V <sub>IH</sub> = 2 V	$I_{OL} = 500 \text{ mA}$		0.28	0.5	
V <sub>R(K)</sub>	Output clamp-diode reverse voltage	$V_{CC} = 4.75 \text{ V},$	I <sub>R</sub> = 100 μA	70	100		V
V <sub>F(K)</sub>	Output clamp-diode forward voltage	IF = 500 mA			1	1.6	V
ЮН	High-level output current	V <sub>CC</sub> = 4.75 V, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 70 V		1	100	μΑ
lн	High-level input current	V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = 5.25 V		0.1	10	μΑ
Ι <sub>Ι</sub> L	Low-level input current	V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = 0.8 V		-0.25	-10	μΑ
Іссн	Supply current, outputs high	$V_{CC} = 5.25 \text{ V},$	V <sub>I</sub> = 0		1	4	mA
ICCL	Supply current, outputs low	$V_{CC} = 5.25 \text{ V},$	V <sub>I</sub> = 5 V		45	65	mA

 $<sup>\</sup>dagger$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high-level output				1950	5000	ns
tPHL	Propagation delay time, high-to-low-level output	C <sub>L</sub> = 30 pF,	$R_L = 60 \Omega$ ,		150	500	ns
tTLH	Transition time, low-to-high-level output	See Figure 1	_		40		ns
tTHL	Transition time, high-to-low-level output				36		ns
VOH	High-level output voltage after switching	$V_S = 35 \text{ V},$ $R_L = 70 \Omega,$	I <sub>O</sub> ≈ 500 mA, See Figure 2	V <sub>S</sub> -10			mV

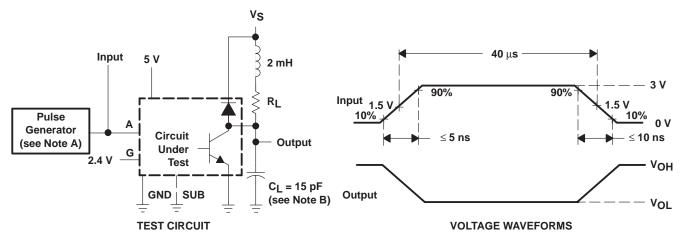
### PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: PRR = 100 kHz,  $Z_O$  = 50  $\Omega$ .

B. C<sub>L</sub> includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms



NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 kHz,  $Z_O = 50 \Omega$ .

B. CL includes probe and jig capacitance.

Figure 2. Latch-Up Test Circuit and Voltage Waveforms



### PACKAGE OPTION ADDENDUM

18-Jul-2006

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75437ANE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75437ANEE4	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

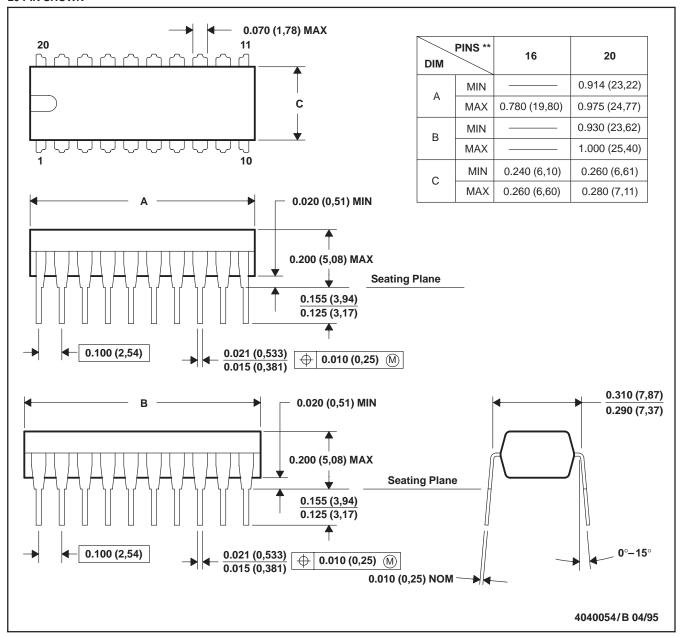
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### NE (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

#### 20 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 (16 pin only)

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